


Full Material Declaration for attached parts list

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	Diotec Semiconductor AG
	DUNS number: 330866844
	-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
	Declarations authorised by: Udo Steinebrunner, Product Manager, -

Declaration effective from: 19 December 2018 [Approved on 04 December 2025, 08:22 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Attach agent	Other nonferrous metals	2.78%	1,1'-Sulphonylbis(4-aminobenzene)	80-08-0	1%
			1,4-BIS(2,3-EPOXYPROPOXY)BUTANE	2425-79-8	7%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	15%
			SILVER, ELEMENTAL	7440-22-4	77%
Chip (die)	Other inorganic materials	12.5%	Elemental silicon	7440-21-3	100%
Encapsulation	EP (Epoxy resin)	43.75%	Carbon black	1333-86-4	1%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	15%
			Amorphous silica	60676-86-0	84%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	2.78%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	1.39%	Tin elemental	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	36.8%	Elemental iron	7439-89-6	2.6%
			COPPER, ELEMENTAL	7440-50-8	97.4%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-523 (JA) PB & H-Free	Diode / Transistor SMD	0.00288	g